



FOR IMMEDIATE RELEASE

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**AEHR TEST SYSTEMS NAMES  
NEW U.S. REPRESENTATIVE FOR DIEPAK SALES**

**FREMONT, CA. (July 18, 2002)** - Aehr Test Systems (Nasdaq: [AEHR](#)), a leading supplier of test and burn-in equipment to semiconductor manufacturers, today announced that it has arranged for Million & Associates to be the sales representative in the United States for Aehr Test's DiePak® carrier product line.

DiePak carriers provide a temporary direct interface between the electronics of a burn-in and test system and unpackaged wire bond or bumped bare die. They provide an efficient, effective means of producing Known-Good Die (KGD), which are bare die that have been screened and qualified for use in multiple-device packages and high-cost single-device packages. When bare die are placed into the DiePak carrier, they are electrically connected to the burn-in board and burn-in and test system electronics. After burn-in, the DiePak carrier can also be used to interface the bare die to a standard tester for performance testing. This allows bare die to be tested to the same standards and with the same burn-in and test equipment as conventionally packaged ICs.

Carl Buck, vice president of Aehr Test Systems, said, "We could not ask for more in Million and Associates' experience and expertise in the burn-in and test business, especially when it concerns bare die. Their involvement enhances the value of our DiePak products by making a dependable source of knowledge and service available to customers who are considering implementing a KGD program."

Bob Million, president of Million & Associates, said, "We are enthusiastic about being associated with Aehr Test, who offers the market-leading product for burning-in and testing bare die. With the rising cost of packaging, we expect the demand for KGD to increase significantly over the next few years. This agreement adds distinction to our stable of products, because the DiePak carrier is a key enabling technology."

Aehr Test will be displaying its DiePak product line at Semicon West, July 17-19, 2002, at the San Jose Convention Center in San Jose, CA.

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### **About Aehr Test Systems**

Headquartered in Fremont, California, Aehr Test Systems is a leading provider of systems for burning-in and testing DRAM and logic integrated circuits and has an installed base of more than 2,000 systems worldwide. Aehr Test has developed and introduced several innovative products, including the FOX™, MTX, MAX3 and MAX4 systems and the DiePak carrier. The FOX system is a full wafer contact burn-in and test system. The MTX system is a massively parallel test system designed to reduce the cost of memory testing by performing both test and burn-in on thousands of devices simultaneously. The MAX system can effectively burn-in and functionally test sophisticated devices, such as digital signal processors, microprocessors, microcontrollers and systems-on-a-chip. The DiePak carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of bare die.

### **About Million and Associates**

Based in Silicon Valley, Million & Associates is a manufacturers' representative with product lines in wafer probes, test sockets, and high-density interconnects. In addition to the DiePak carrier product line, their solutions include probe cards for wafer level testing and performance test sockets for development, prototyping and testing of integrated circuits for the latest high-speed technologies.

### **Safe Harbor Statement**

This release contains forward-looking statements that involve risks and uncertainties relating to projections regarding industry growth and customer demand for the Company's products. Actual results may vary from projected results. These risks and uncertainties include economic conditions in Asia and elsewhere, world events, acceptance by customers of the FOX, MTX, MAX and DiePak technologies, the Company's development and manufacture of a commercially successful wafer-level burn-in system, and the potential emergence of alternative technologies, which could adversely affect demand for the Company's products in fiscal year 2003. See the Company's latest 10-K and 10-Q reports filed with the SEC for additional risks affecting the Company.

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